

深圳市森科泰电子有限公司

产品规格书

SPECIFICATION

DESCRIPTION **Chip Antenna**

PART NO. **SKT321606-CD-01-R**

VERSION **V2.1**

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1. Naming Rules

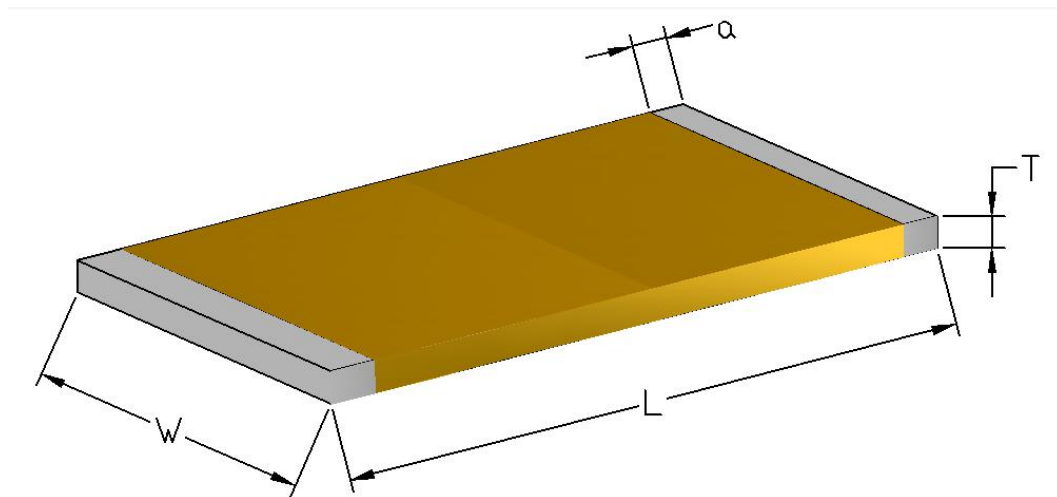
Type: SKT-ABCDEF-GH-IJ-K

1. SKT: Shortcut for Thinkte
2. ABCDEF: AB: Length(mm) CD: Width(mm)
 For example: 502010 5.0mm*2.0mm
3. G: Material (C- Ceramic P-Polymer)
4. H: Feeding (S- Single D - Dual)
5. I J: Version (01 - 99)
6. K: Package (R - Reel, T - Tape)

2. Antenna Specification

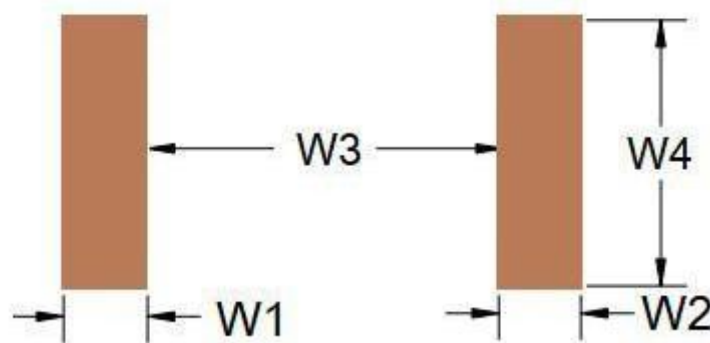
Outline Dimensions	3.2x1.6x0.6(mm)
Ground Plane	3.2x1.6(mm)
Frequency Range	2.4GHz ~ 2.5GHz
Impedance	50 Ohm Nominal
Bandwidth (under -10dB return loss)	110MHz (Typ.)
Radiation	Omni-directional
Peak Gain	1.75 dBi (Typ.)
Efficiency	60% (Typ.)
Polarization	Linear Polarization
Storage Temp	-40℃ ~ +85℃
Color	Brown

3. Antenna Dimension



Type	L	W	T	a
SKT3216	3.2 ±0.2	1.6 ±0.2	0.6 ±0.2	0.4 ±0.2

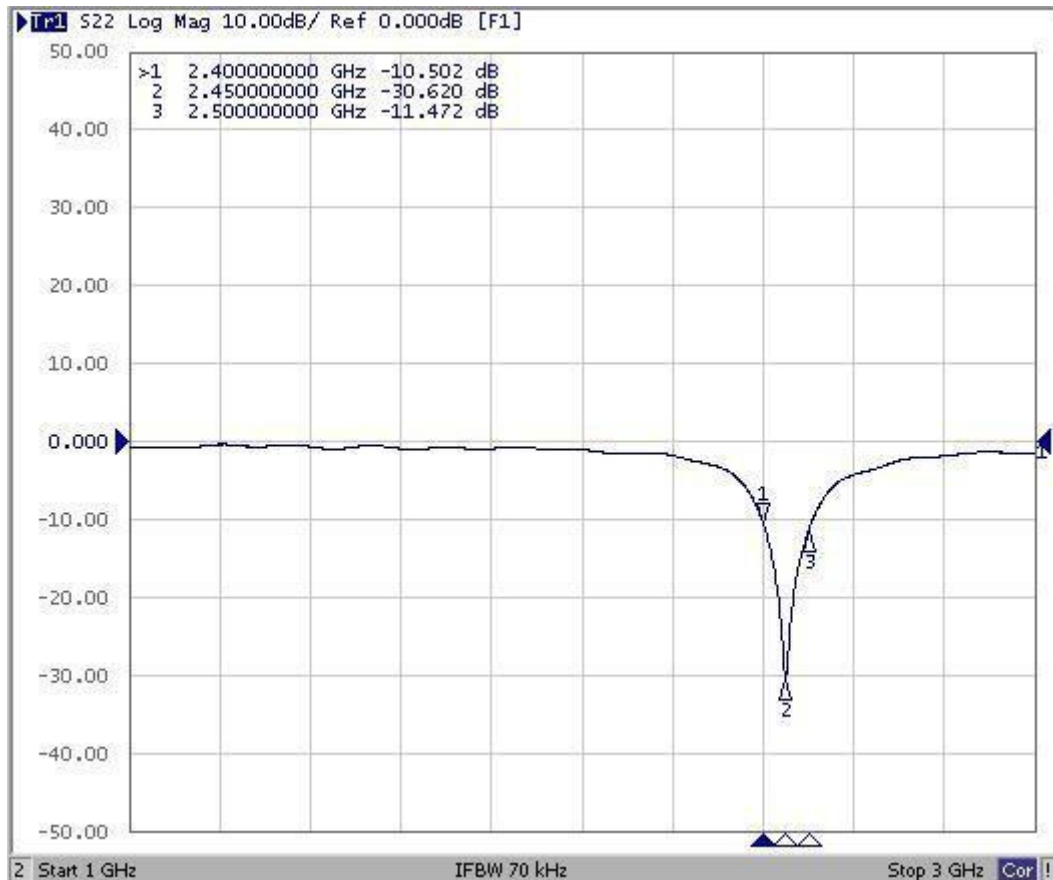
FootPrint (Unit : mm)



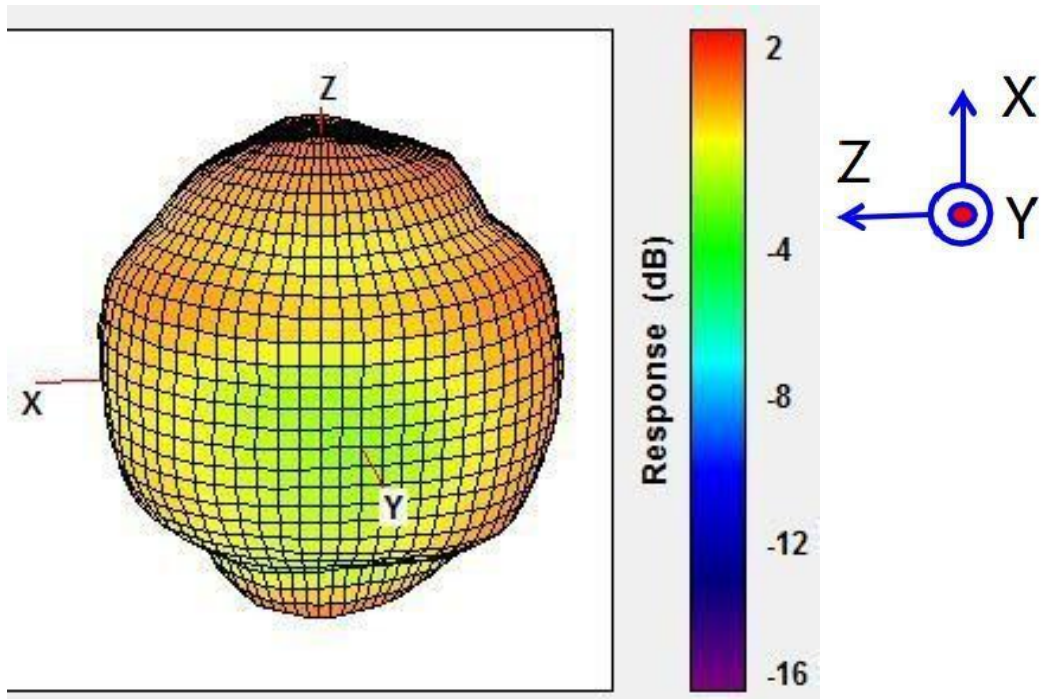
Type	W1	W2	W3	W4
SKT3216	0.4 ±0.2	0.4 ±0.2	2.4 ±0.2	1.6 ±0.2

4. Test Data:

3.1 ELECTRICAL CHARACTERISTICS

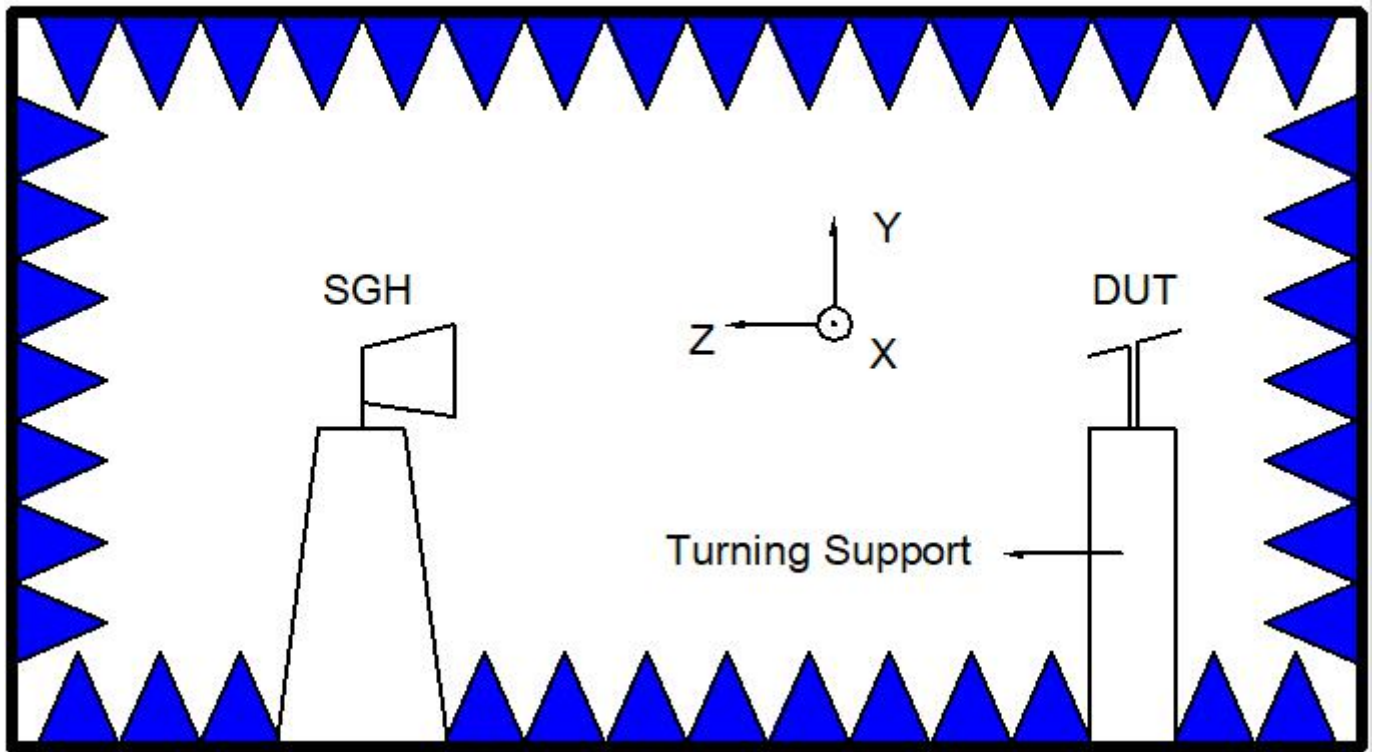


3.2 Radiation Pattern



	Efficiency	Peak Gain	Directivity
2400MHz	57.45%	1.3 dBi	2.45 dBi
2450MHz	60.65%	1.75dBi	2.89 dBi
2500MHz	56.75%	1.45dBi	2.23 dBi

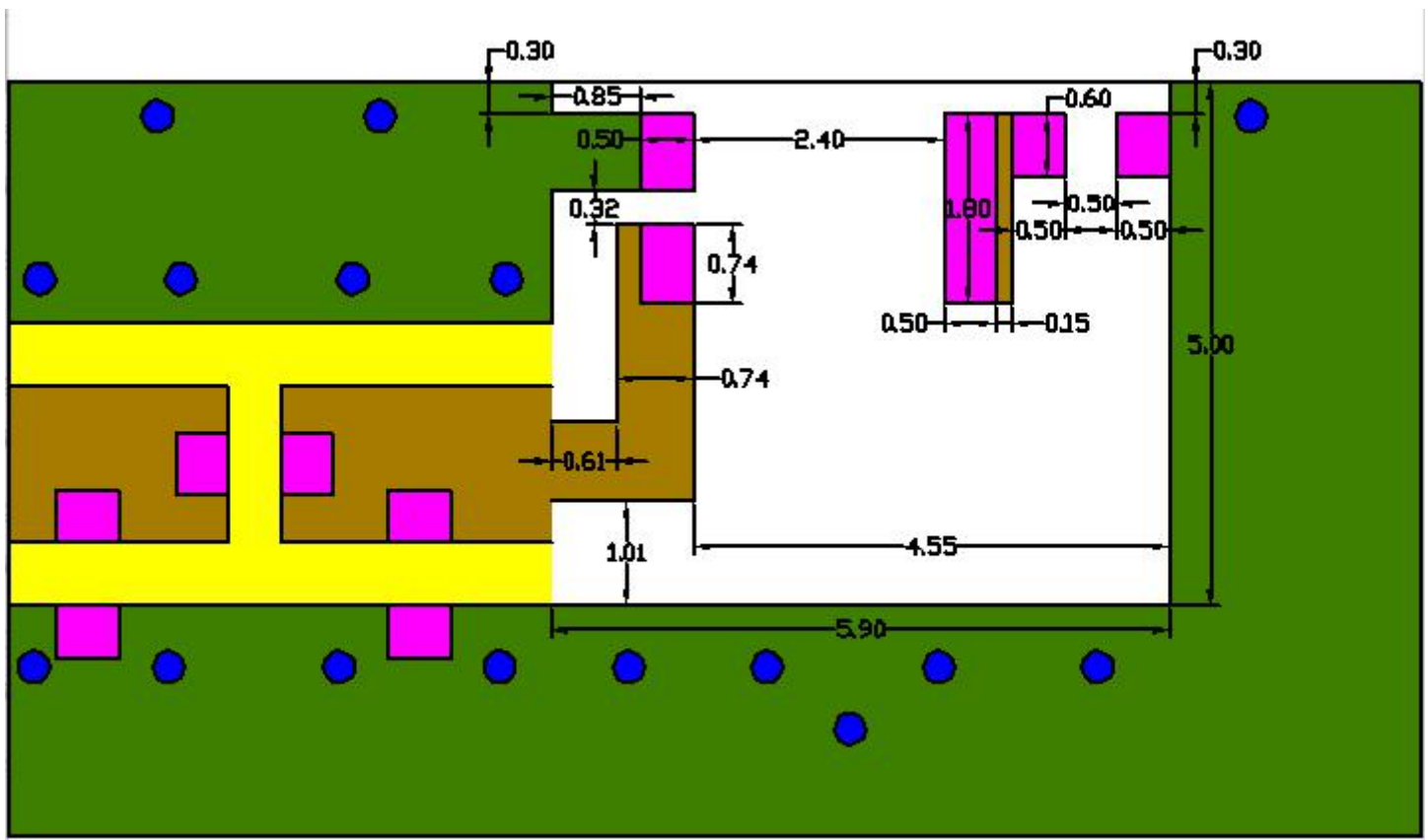
Chamber Coordinate System



5. LayoutGuide:

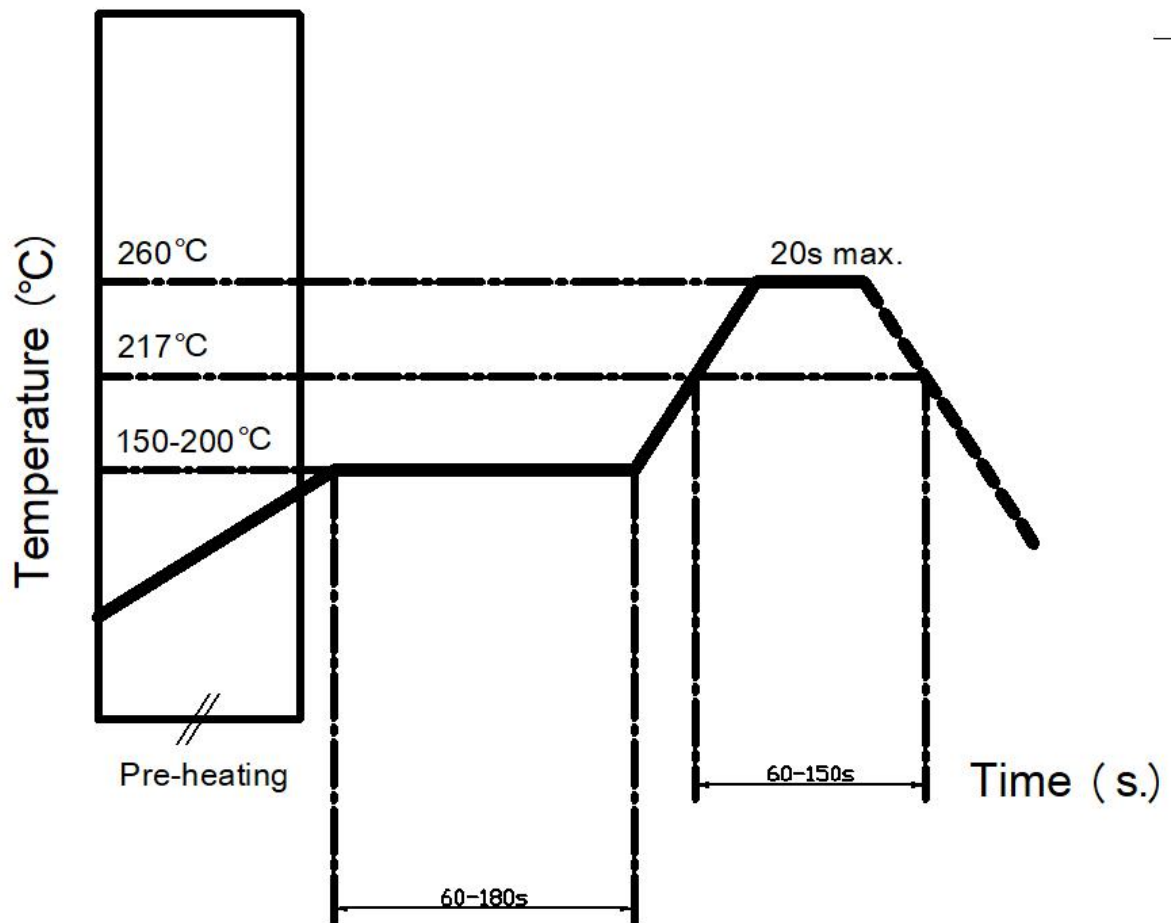
Solder Land Pattern:

Land pattern for soldering (black marking areas) is as shown below. Matching circuit is needed for good performance, when customer's device is different.



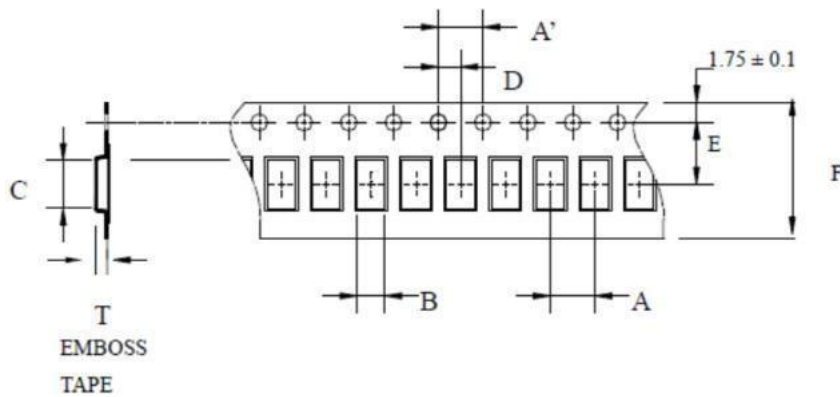
6.Soldering Conditions:

Typical Soldering Profile for Lead-free Process



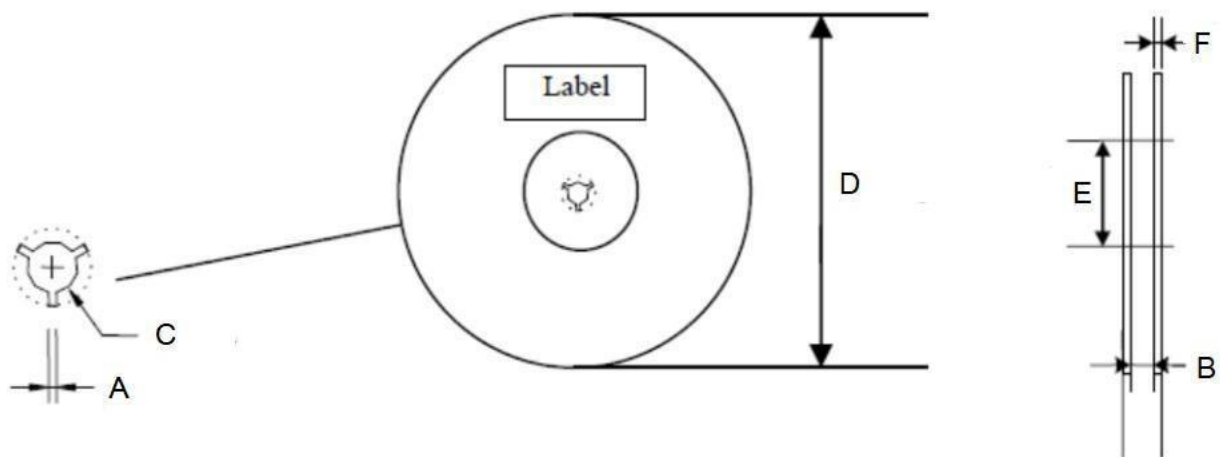
7. Taping Specifications:

Tape Dimensions (Unit: mm) & Quantity



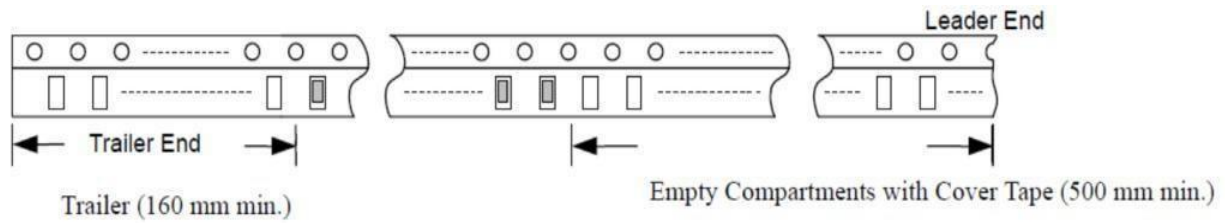
Type	A	A'	B	C	D	E	F	T	Quantity/ Reel	Type Material
SKT3216	4.0 ± 0.1	4.0 ± 0.1	1.95 ± 0.1	3.50 ± 0.1	2.0 ± 0.05	3.5 ± 0.1	8.0 ± 0.1	0.85 ± 0.1	4,000pcs	Plastic (Embossed)

Reel Dimensions (Unit: mm)



Type	A	B	C	D	E	F
SKT3216	2.3 ± 0.5	17 ± 0.5	13.5 ± 0.5	178 ± 1	75 ± 3	1.4 ± 0.2

Leader and Trailer Tape



Soldering Conditions:

- (1) Temperature: 5~35°C, relative humidity (RH): 45~75%.
- (2) Non-corrosive environment